

InspireSemi™

Disruptive Next Generation Accelerated
Computing Platform

Blistering speed, energy efficiency,
versatility, and affordability for HPC/AI
and graph analytics applications

Company Overview

December 2024

Disclaimer

This presentation contains statements which constitute “forward-looking information” within the meaning of applicable securities laws, including statements regarding the plans, intentions, beliefs and current expectations of InspireSemi with respect to future business activities and operating performance.

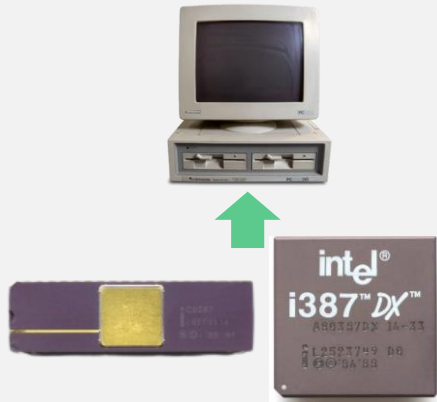
Often, but not always, forward-looking information can be identified by the use of words such as “plans”, “expects”, “is expected”, “budget”, “scheduled”, “estimates”, “forecasts”, “intends”, “anticipates”, or “believes” or variations (including negative variations) of such words and phrases, or statements formed in the future tense or indicating that certain actions, events or results “may”, “could”, “would”, “might” or “will” (or other variations of the forgoing) be taken, occur, be achieved, or come to pass. Forward-looking information includes, but is not limited to, information regarding: (i) the business plans and expectations of the Company including expectations with respect to production and development; and (ii) expectations for other economic, business, and/or competitive factors. Forward-looking information is based on currently available competitive, financial and economic data and operating plans, strategies or beliefs as of the date of this presentation, but involve known and unknown risks, uncertainties, assumptions and other factors that may cause the actual results, performance or achievements of InspireSemi, to be materially different from any future results, performance or achievements expressed or implied by the forward-looking information. Such factors may be based on information currently available to InspireSemi, including information obtained from third-party industry analysts and other third-party sources, and are based on management’s current expectations or beliefs. Any and all forward-looking information contained in this presentation is expressly qualified by this cautionary statement.

Investors are cautioned that forward-looking information is not based on historical facts but instead reflect InspireSemi’s management’s expectations, estimates or projections concerning future results or events based on the opinions, assumptions and estimates of management considered reasonable at the date the statements are made. Forward-looking information reflects InspireSemi’s current beliefs and is based on information currently available to it and on assumptions it believes to be not unreasonable in light of all of the circumstances. In some instances, material factors or assumptions are discussed in this presentation in connection with statements containing forward-looking information. Such material factors and assumptions include, but are not limited to: the impact of the COVID-19 pandemic on the Transaction or the company; the ongoing conflict between Russia and Ukraine and any actions taken by other countries in response thereto, such as sanctions or export controls; and anticipated and unanticipated costs and other factors referenced in this presentation and the Filing Statement, including, but not limited to, those set forth in the Filing Statement under the caption “Risk Factors”. Although the Company has attempted to identify important factors that could cause actual actions, events or results to differ materially from those described in forward-looking information, there may be other factors that cause actions, events or results to differ from those anticipated, estimated or intended. Forward-looking information contained herein is made as of the date of this presentation and, other than as required by law, the Company disclaims any obligation to update any forward-looking information, whether as a result of new information, future events or results or otherwise. There can be no assurance that forward-looking information will prove to be accurate, as actual results and future events could differ materially from those anticipated in such statements. Accordingly, readers should not place undue reliance on forward-looking information. Should one or more of these risks or uncertainties materialize, or should assumptions underlying the forward-looking information prove incorrect, actual results may vary materially from those described herein as intended, planned, anticipated, believed, estimated or expected.

The Third Wave of Accelerated Computing is Here

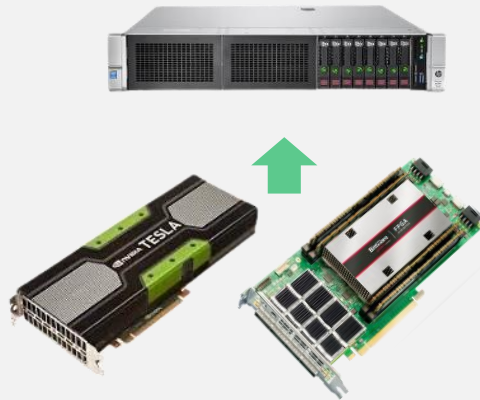
Thunderbird for HPC, AI, Graph Analytics

1980 Math Coprocessor



- Purpose-built widely applicable
- Open software ecosystem
- Plugs into existing computers

2007 GPU, FPGA



- Limited applications benefit
- Proprietary software model
- Plugs into existing servers



2025+ Thunderbird

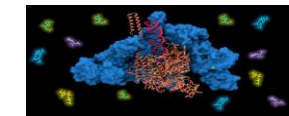
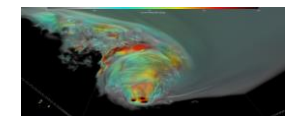
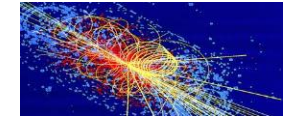
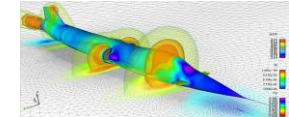
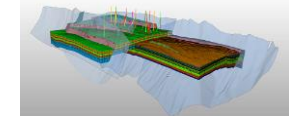
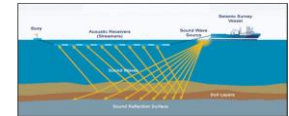
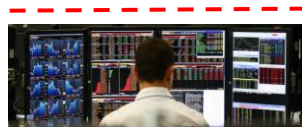


- Built for HPC
- Versatile & open software ecosystem
- Plugs into existing servers



Addressing the Need to Accelerate All HPC & AI Software

What customers always wanted...not “yet another GPU”



Financial simulations

Geology: Seismic

Financial Trading & Graph Analytics

Energy: Reservoir Modeling & Sim

CAE/Computational Fluid Dynamics

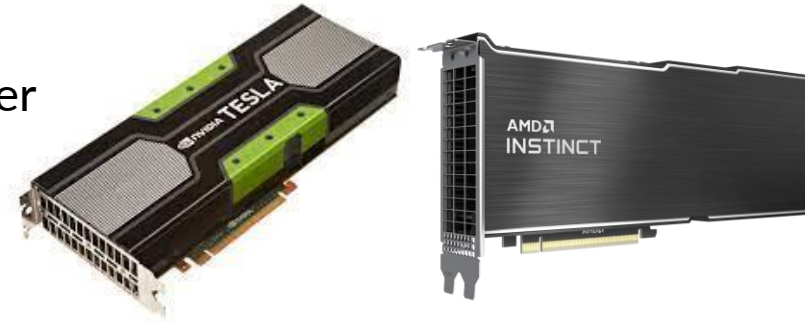
Government Lab Simulations

Climate & Weather Modeling

Cybersecurity & Cryptography

Genomics, Pharma, Life Sciences

Datacenter GPUs



InspireSemi Thunderbird



Highly differentiated “supercomputer-cluster-on-a-chip”

- Versatile platform delivers unprecedented capability
- 4 chip PCIe card delivers >6,000 64-bit CPU cores (FP64)
- Innovative high-bandwidth, low-latency on-chip network
- Best-in-class for both Performance/\$ and Watt
- Large scale computing power with much lower TCO - can replace many racks of servers and expensive high-speed networking

Thunderbird Designed Specifically to Meet the Needs of the Underserved HPC/AI Industry

- It's **powerful**: Board with 6,000+ CPU cores delivers high precision 64 bit performance
- It's **fast**: Proprietary low-latency mesh network on chip = 5-10x faster core-to-core communication
- It's **cost effective**: Disruptive price point AND less expensive to operate than existing solutions
- It's **green**: Best in class energy efficiency
- It's **straightforward**: PCIe card fits right into any standard server
- It's **liberating**: Our open-source ecosystem doesn't force proprietary software
- It's **versatile**: Widely applicable: double-precision math, AI, fully deterministic
- It's **easier**: Users can confidently port their existing programs
- It's **scalable**: Customers with substantial needs can quickly scale up to 256 chips
- **Recognized global partners** across multiple markets and geographies



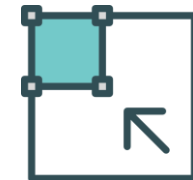
Thunderbird Datacenter Impact:

Significant datacenter TCO savings and carbon footprint reduction

- Thunderbird has >20X CPU cores vs. Intel/AMD CPU cores per board
 - Intel and AMD CPUs: Latest have 256 bloated cores per board
 - Thunderbird I: 6,144 custom, low-power, low-area cores per board
- One Thunderbird card has more CPU cores than an **entire rack of standard Intel/AMD servers!**
 - Less complexity, servers, power, HVAC, interconnects, points of failure, real estate



4U Server with 8 Thunderbird cards



InspireSemi Thunderbird in the News

techradar.

Supercomputer-on-a-chip goes live: single PCIe card packs more than 6,000 RISC-V cores, with the ability to scale to more than 360,000 cores

- InspireSemi has announced the successful tapeout of the Thunderbird I Accelerated Computing chip for fabrication at TSMC

tom's HARDWARE

Thunderbird packs up to 6,144 CPU cores into a single AI accelerator and scales up to 360,000 cores — InspireSemi's RISC-V 'supercomputer-cluster-on-a-chip' touts higher performance than Nvidia GPUs

- The Holy Grail of supercomputing chip design is an architecture that combines the versatility and programmability of CPUs with the explicit parallelism of GPUs, and InspireSemi strives to achieve just that

TECHSPOT

Move over GPUs, with 1,536 cores the Thunderbird RISC-V CPU is ready to eat your lunch

- Open source enables small industries to participate in the accelerator boom

ALL ABOUT CIRCUITS

InspireSemi Announces Tapeout of Thunderbird Accelerated Computing Chip

- InspireSemi's new compute chip couples the parallel processing of GPUs with the versatility of CPUs

JPR
Jon Peddie Research

InspireSemi announces tape-out of RISC-V HPC chip

- InspireSemi's Thunderbird I RISC-V chip offers high-performance computing for underserved applications, with an emphasis on energy efficiency and competitive pricing

Sample Thunderbird Customer & Partner Feedback



“The pursuit of AI has been a tremendous boon for high-performance architectures across the board. For pure AI investments, most of the attention is on GPUs, but many organizations are seeking a more versatile solution, built on processing elements that are suited to a variety of HPC, AI, and analytics workloads. This is where we see a market opportunity for companies like InspireSemi with its Thunderbird platform.”

- *Adison Snell, CEO*



“Sandia is pleased to have joined InspireSemi’s early access program for their upcoming Thunderbird processor. This is enabling us to engage early by evaluating our challenging application workloads on Thunderbird’s massively parallel interconnected CPU architecture, helping to mature the overall RISC-V HPC software stack, and providing our input for future versions of Thunderbird.”

- *Kevin Pedretti, Principal Member of Technical Staff, Scalable System Software*



“With the momentum of AI and the convergence of AI and HPC, it is time to look outside the status quo and leverage a new technology base, like InspireSemi’s Thunderbird product line. Thunderbird is ideal for workflows that require the highest performance and lowest power. It is easy to integrate, making it a valuable addition to the HPC and AI industry.”

- *Earl J. Dodd, Global HPC Business Practice Leader*



“The combination of your custom designed RISC-V ‘sea of cores’ plus high-speed interconnect fabric is very smart, and your decision to focus on HPC (and blockchain opportunistically) rather than AI/ML was likewise very smart.”

- *Amit Nanda, Advanced Tech Sourcing*



“This will let us run large memory simulations with AI workflows. We will take anything you can give sooner.”

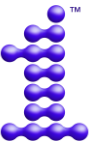
- *Rajeev Thakur, Deputy Director, Data Science and Learning Division*

Open Software Ecosystem Solves Customer Porting Challenges

- Supports standard operating systems (unlike competing compute accelerators)
 - **Linux!** (more on next slide)
 - Real-Time Operating Systems (RTOS)
 - Kitten lightweight kernel (LWK for DOE labs)
 - Eliminates need to learn and use proprietary software stacks
 - Eliminates vendor lock-in
- Uses standard CPU-style programming models
 - No need for CUDA, ROCM, etc. that GPUs require
 - No need for disruptive software algorithm rewrites
 - Standard compiler, OpenMP, MPI, etc. approaches
- Leverages key RISC-V software ecosystem
 - Address-accurate QEMU model
 - Standard compilers, e.g.- GCC, Gfortran, GDB toolchains
 - Standard HPC libraries, e.g. – BLAS, LAPACK, FFTW



Zephyr®



oneAPI



TensorFlow



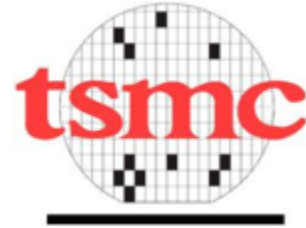
Linux on Thunderbird - Customer Benefits

- No competing compute accelerator runs Linux (or any other standard operating system)
- The HPC/AI industry loves Linux and open source software
- Provides access to the entire existing HPC/AI software ecosystem
- Customers and software companies can utilize the Linux software stack we provide and immediately begin developing or tuning their custom applications

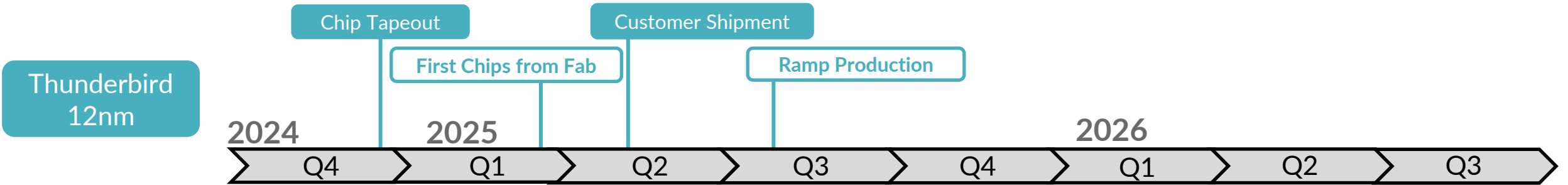


World Class Supply Chain Partners

- TSMC - Wafer fab
 - World's largest semiconductor foundry
 - Developing the most advanced process nodes
 - Secured 12nm wafer capacity for 2024+
- ASE – Chip package & test
 - Worlds largest and highest quality OSAT (Outsourced Semiconductor Assembly and Test)
 - Leading edge package design
- Imec: Value Chain Aggregator (VCA)
 - Enable early access to tier-1 supply chain
 - Support engineering and early-prod volumes



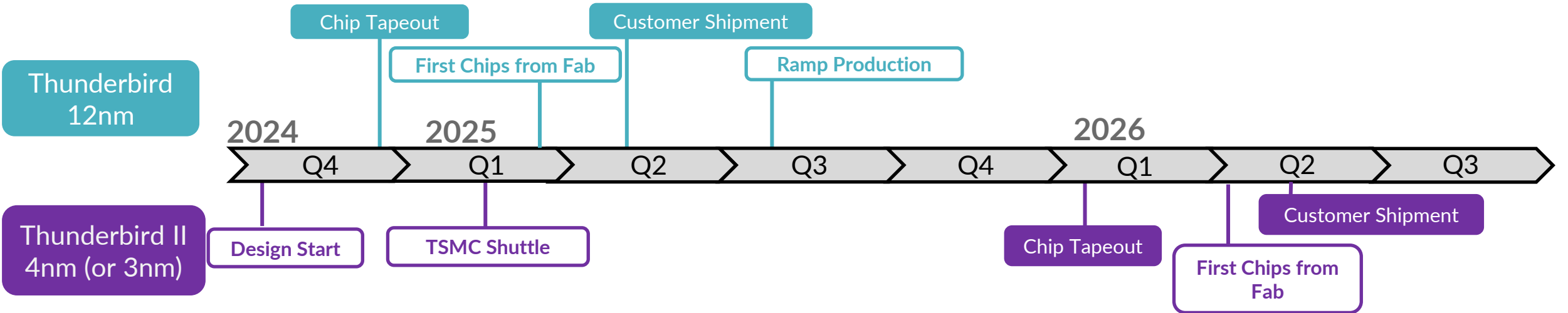
Robust HPC & AI Roadmap



Thunderbird

- Addresses complex HPC applications
 - e.g.- CAE/CFD, energy/reservoir modeling & sim, weather, pharma/genomics, finance, fraud detection
 - Low-cost DDR memory for large HPC jobs
- Ideal for graph analytics
- Applicable for AI-augmented HPC
- Apps requiring determinism; e.g.- robotics, cryptography, smart weapons, health imaging

Robust HPC & AI Roadmap



Thunderbird

- Addresses complex HPC applications
 - e.g.- CAE/CFD, energy/reservoir modeling & sim, weather, pharma/genomics, finance, fraud detection
 - Low-cost DDR memory for large HPC jobs
- Ideal for graph analytics
- Applicable for AI-augmented HPC
- Apps requiring determinism; e.g.- robotics, cryptography, smart weapons, health imaging

Thunderbird II

- TSMC 4(3) nm – higher performance, lower power
 - Quadruples core count, larger cache sizes
- Additional features for AI
 - High Bandwidth Memory (HBM), UXL
 - AI-specific instructions
- Enhanced vector instructions for HPC

Thunderbird Addresses ALL HPC & AI Customer Needs

	InspireSemi Thunderbird	CPU	GPU	FPGA	AI Accelerators
Architecture	Many programs, many data streams	Few programs, few data streams	Few programs, many data streams	Programmable logic elements	Single program, many data streams
Performance	High for broad range of HPC apps	Slow, need h/w accelerators	High for AI and some HPC apps	Medium	High for AI only
Cost	Low \$6,500 for 2 chip PCIe card	High ~\$1K-8K (+ more servers)	High ~\$7K-48K	High \$8K-\$10K	High ~\$10K - \$2.2M
Energy consumption	Low ~50W/chip (150W max)	Med 290W+/chip (+ more servers)	High ~700W	High ~300W	High ~300W - 20kW
Scalability	256 chips	1-4 chips	2-8 chips	1 chip	1-2 chips
Programming model	Standard CPU-like, Any language, Full instruction set	Standard CPU, Any language, Full instruction set	Specialized C variant (CUDA, ROCM, SYCL)	Hardware description language	Proprietary, obscure
Software ecosystem	Open-source, Linux, compilers, libraries, AI frameworks, existing applications	Robust	Limited, proprietary	None	AI frameworks and proprietary software stacks

Accomplished Leadership Team



Alexander Gray, Founder, President & CTO

- 15 years experience in tech startups, entrepreneurship
- CryptoCore, SolarBridge, SunPower
- Holds 9 patents
- BSEE, University of Illinois at Urbana-Champaign



Thomas Fedorko, COO

- 35+ years hands-on technical and business leadership in semiconductor operations in both large IDM and startups
- Eta Compute, Uhnder, Bluetechnix, Black Sand (Qualcomm), Luminary Micro (TI), Oak Technology, Motorola SPS
- Technical degree from DeVry University and graduate of the Motorola Management Institute



Ron Van Dell, CEO

- 40 years experience and an exceptional track record of success and proven leadership skills in early-stage, turn-around and established businesses
- Former CEO of Primarion (Infineon), SolarBridge, and several other semiconductor and hardware startups
- GM Dell, VP-GM of Communication Products at Harris Semi (Intersil/Renesas)
- BSEE, Michigan Technological University



Doug Norton, CMO

- 35+ years experience; enterprise, startups, Federal
- Viviota, Nimbix, TMT, Virtana, Newisys, CoWare (Synopsys), Cadence, IBM
- President of Society of HPC Professionals, UT ATI mentor (Austin Technology Incubator at University of Texas)
- RISC-V International: member SIG-HPC & Marketing team
- BSEE, Missouri University of Science and Technology



Jack Cartwright, Interim CFO

- 20+ years experience in tech startups and public companies
- Datum, Spruce Services, BT Global, Atkins Global, Cisco
- Former US Army Logistics & Operations officer
- MBA, University of Texas; MS Accounting, University of Miami

